# **Secondary Side Post** Regulator for AC/DC and **DC/DC** Multiple Output **Converters**

The CS5101 is a bipolar monolithic secondary side post regulator (SSPR) which provides tight regulation of multiple output voltages in AC/DC or DC/DC converters. Leading edge pulse width modulation is used with the CS5101.

The CS5101 is designed to operate over an 8.0 V to 45 V supply voltage (V<sub>CC</sub>) range and up to a 75 V drive voltage (V<sub>C</sub>).

The CS5101 features include a totem pole output with 1.5 A peak output current capability, externally programmable overcurrent protection, an on chip 2.0% precision 5.0 V reference, internally compensated error amplifier, externally synchronized switching frequency, and a power switch drain voltage monitor. It is available in a 14 lead plastic DIP or a 16 lead wide body SOIC package.

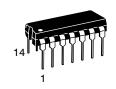
#### **Features**

- 1.5 A Peak Output (Grounded Totem Pole)
- 8.0 V to 75 V Gate Drive Voltage
- 8.0 V to 45 V Supply Voltage
- 300 ns Propagation Delay
- 1.0% Error Amplifier Reference Voltage
- Lossless Turn On and Turn Off
- Sleep Mode: < 100 μA
- Overcurrent Protection with Dedicated Differential Amp
- Synchronization to External Clock
- External Power Switch Drain Voltage Monitor
- Pb-Free Packages are Available\*



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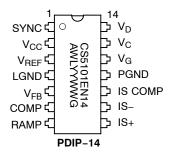


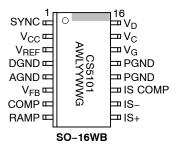
PDIP-14 **N SUFFIX CASE 646** 



**SO-16WB DW SUFFIX CASE 751G** 

### **MARKING DIAGRAMS AND PIN ASSIGNMENTS**





= Assembly Location

WL = Wafer Lot VV = Year WW = Work Week = Pb-Free Package

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

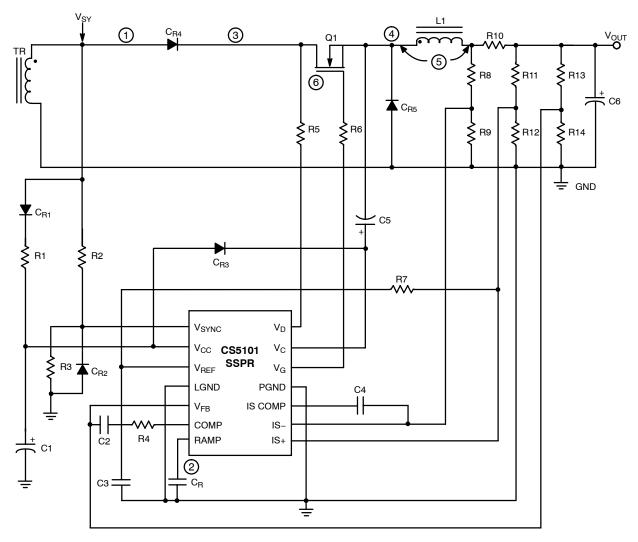


Figure 1. Application Diagram

### **MAXIMUM RATINGS**

Rat	Value	Unit	
Power Supply Voltage, V <sub>CC</sub>		-0.3 to 45	V
V <sub>SYNC</sub> and Output Supply Voltages, V <sub>C</sub> , V <sub>G</sub> , V <sub>SYNC</sub> ,	, V <sub>D</sub>	-0.3 to 75	V
V <sub>IS+</sub> , V <sub>IS-</sub> (V <sub>CC</sub> – 4.0 V, up to 24 V)		-0.3 to 24	V
V <sub>REF</sub> , V <sub>FB</sub> , V <sub>COMP</sub> , V <sub>RAMP</sub> , V <sub>ISCOMP</sub>		-0.3 to 10	V
Operating Junction Temperature, T <sub>J</sub>		-40 to +150	°C
Operating Temperature Range		-40 to +85	°C
Storage Temperature Range		-65 to +150	°C
Output Energy (Capacitive Load Per Cycle)		5.0	μJ
ESD Human Body		2.0	kV
Lead Temperature Soldering	Wave Solder (through hole styles only) (Note 1) Reflow (SMD styles only) (Note 2)	260 peak 230 peak	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. 10 second maximum
- 2. 60 second maximum above 183°C

**ELECTRICAL CHARACTERISTICS** ( $-40^{\circ}\text{C} \le T_{A} \le 85^{\circ}\text{C}$ ,  $-40^{\circ}\text{C} \le T_{J} \le 150^{\circ}\text{C}$ ,  $10 \text{ V} < V_{CC} < 45 \text{ V}$ ,  $8.0 \text{ V} < V_{C} < 75 \text{ V}$ ; unless otherwise specified.)

Characteristic	Test Conditions	Min	Тур	Max	Unit
Error Amplifier				1	l .
Input Voltage Initial Accuracy	V <sub>FB</sub> = V <sub>COMP</sub> , V <sub>CC</sub> = 15 V, T = 25°C, Note 3	1.98	2.00	2.02	V
Input Voltage			2.00	2.06	V
nput Bias Current $V_{FB} = 0 \text{ V, IV}_{FB}$ flows out of pin		_	_	500	nA
Open Loop Gain	1.5 V < V <sub>COMP</sub> < 3.0 V	60	70	_	dB
Unity Gain Bandwidth	1.5 V < V <sub>COMP</sub> < 3.0 V, Note 3	0.7	1.0	_	MHz
Output Sink Current	V <sub>COMP</sub> = 2.0 V, V <sub>FB</sub> = 2.2 V	2.0	8.0	-	mA
Output Source Current	V <sub>COMP</sub> = 2.0 V, V <sub>FB</sub> = 1.8 V	2.0	6.0	-	mA
V <sub>COMP</sub> High	V <sub>FB</sub> = 1.8 V	3.3	3.5	3.7	V
V <sub>COMP</sub> Low	V <sub>FB</sub> = 2.2 V	0.85	1.0	1.15	V
PSRR	10 V < V <sub>CC</sub> < 45 V, V <sub>FB</sub> = V <sub>COMP</sub> , Note 3	60	70	_	dB
Voltage Reference		l	l .		I
Output Voltage Initial Accuracy	V <sub>CC</sub> = 15 V, T = 25°C, Note 3	4.9	5.0	5.1	V
Output Voltage	0 A < I <sub>REF</sub> < 8.0 mA	4.8	5.0	5.2	V
Line Regulation	10 V < V <sub>CC</sub> < 45 V, I <sub>REF</sub> = 0 A	_	10	60	mV
Load Regulation	0 A < I <sub>REF</sub> < 8.0 mA	_	20	60	mV
Current Limit	V <sub>REF</sub> = 4.8 V	10	50	_	mA
V <sub>REF</sub> _OK FAULT V	$V_{SYNC} = 5.0 \text{ V}, V_{REF} = V_{LOAD}$	4.10	4.40	4.60	V
V <sub>REF</sub> OK V	V <sub>SYNC</sub> = 5.0 V, V <sub>REF</sub> = V <sub>LOAD</sub>	4.30	4.50	4.80	V
V <sub>REF</sub> OK Hysteresis	-	40	100	250	mV
Current Sense Amplifier		I	l .		I
IS COMP High V	IS+ = 5.0 V, IS- = IS COMP	4.7	5.0	5.3	V
IS COMP Low V	IS+ = 0 V, IS- = IS COMP	0.5	1.0	1.3	V
Source Current	IS+ = 5.0 V, IS- = 0 V	2.0	10	-	mA
Sink Current	IS- = 5.0 V, IS+ = 0 V	10	20	_	mA
Open Loop Gain	1.5 V ≤ $V_{COMP}$ ≤ 4.5 V, $R_L$ = 4.0 kΩ	60	80	-	dB
CMRR	Note 3	60	80	-	dB
PSRR	10 V < V <sub>CC</sub> < 45 V, Note 3	60	80	-	dB
Unity Gain Bandwidth	1.5 V ≤ $V_{COMP}$ ≤ 4.5 V, $R_L$ = 4.0 kΩ, Note 3	0.5	0.8	-	MHz
Input Offset Voltage	$V_{IS}$ + = 2.5 V, $V_{IS}$ - = $V_{ISCOMP}$	-8.0	0	8.0	mV
Input Bias Currents	$V_{IS}$ + = $V_{IS}$ - = 0 V, $I_{IS}$ flows out of pins	_	20	250	nA
Input Offset Current (IS+, IS-)	-	-250	0	250	nA
Input Signal Voltage Range	Note 3	-0.3	-	V <sub>CC</sub> - 4.0	V
RAMP/SYNC Generator					
RAMP Source Current Initial Accuracy	V <sub>SYNC</sub> = 5.0 V, V <sub>RAMP</sub> = 2.5 V, T = 25°C, Note 3	0.18	0.20	0.22	mA
RAMP Source Current	V <sub>SYNC</sub> = 5.0 V, V <sub>RAMP</sub> = 2.5 V	0.16	0.20	0.24	mA
RAMP Sink Current V <sub>SYNC</sub> = 0 V, V <sub>RAMP</sub> = 2.5 V		1.0	4.0	-	mA
RAMP Peak Voltage V <sub>SYNC</sub> = 5.0 V		3.3	3.5	3.7	V
RAMP Valley Voltage	V <sub>SYNC</sub> = 0 V	1.4	1.5	1.6	V
RAMP Dynamic Range	V <sub>RAMPDR</sub> = V <sub>RAMPPK</sub> - V <sub>RAMPVY</sub>	1.7	2.0	2.3	V
RAMP Sleep Threshold Voltage	V <sub>RAMP</sub> @ V <sub>REF</sub> < 2.0 V	0.3	0.6	1.0	V
SYNC Threshold	V <sub>SYNC</sub> @ V <sub>RAMP</sub> > 2.5 V	2.3	2.5	2.7	V
SYNC Input Bias Current	V <sub>SYNC</sub> = 0 V, I <sub>SYNC</sub> flows out of pin	_	1.0	20	μΑ
SYNC - 0 V, ISYNC HOWS OUT OF PITT			_	_	_

Guaranteed by design. Not 100% tested in production.

 $\textbf{ELECTRICAL CHARACTERISTICS} \ (-40^{\circ}\text{C} \le T_{A} \le 85^{\circ}\text{C}, \ -40^{\circ}\text{C} \le T_{J} \le 150^{\circ}\text{C}, \ 10 \ V < V_{CC} < 45 \ V, \ 8.0 \ V < V_{C} < 75 \ V; \ unless otherwise specified.)$ 

Characteristic	Test Conditions	Min	Тур	Max	Unit
Output Stage					
V <sub>G</sub> , High	V <sub>SYNC</sub> = 5.0 V, IV <sub>G</sub> = 200 mA, V <sub>C</sub> - V <sub>G</sub>		1.6	2.5	V
V <sub>G</sub> , Low	V <sub>SYNC</sub> = 0 V, IV <sub>G</sub> = 200 mA	-	0.9	1.5	V
V <sub>G</sub> Rise Time	Switch $V_{SYNC}$ High, $C_G$ = 1.0 nF, $V_{CC}$ = 15 V, measure 2.0 V to 8.0 V	-	30	75	ns
V <sub>G</sub> Fall Time	Switch V <sub>SYNC</sub> Low, C <sub>G</sub> = 1.0 nF, V <sub>CC</sub> = 15 V, measure 8.0 V to 2.0 V	-	40	100	ns
V <sub>G</sub> Resistance to GND	Remove supplies, V <sub>G</sub> = 10 V	-	50	100	kΩ
V <sub>D</sub> Resistance to GND Remove supplies, V <sub>D</sub> = 10 V		500	1500	_	Ω
General					
I <sub>CC</sub> , Operating V <sub>SYNC</sub> = 5.0 V		-	12	18	mA
I <sub>CC</sub> in UVL	/L V <sub>CC</sub> = 6.0 V		300	500	μА
I <sub>CC</sub> in Sleep Mode High	in Sleep Mode High $V_{RAMP} = 0 \text{ V}, V_{CC} = 45 \text{ V}$		80	200	μА
CC in Sleep Mode Low V <sub>RAMP</sub> = 0 V, V <sub>CC</sub> = 10 V		-	20	50	μА
I <sub>C</sub> , Operating High	, Operating High $V_{SYNC} = 5.0 \text{ V}, V_{FB} = V_{IS} - = 0 \text{ V}, V_C = 75 \text{ V}$		4.0	8.0	mA
I <sub>C</sub> , Operating Low	V <sub>SYNC</sub> = 5.0 V, V <sub>FB</sub> = V <sub>IS</sub> - = 0 V, V <sub>C</sub> = 8.0 V	-	3.0	6.0	mA
UVLO Start Voltage –		7.4	8.0	9.2	V
UVLO Stop Voltage –		6.4	7.0	8.3	V
JVLO Hysteresis –		0.8	1.0	1.2	٧
Leading Edge, $t_{DELAY}$ $V_{SYNC} = 2.5 \text{ V to } V_G = 8.0 \text{ V}$		-	280	_	ns
Trailing Edge, $t_{DELAY}$ $V_{SYNC} = 2.5 \text{ V to } V_G = 2.0 \text{ V}$		_	750	-	ns

### **PACKAGE PIN DESCRIPTION**

PACKAGE LEAD #					
PDIP-14	SO-16WB	LEAD SYMBOL	FUNCTION		
1	1	SYNC	Synchronization input.		
2	2	V <sub>CC</sub>	Logic supply (10 V to 45 V).		
3	3	V <sub>REF</sub>	5.0 V voltage reference.		
4	-	LGND	Logic level ground (analog and digital ground tied).		
5	6	V <sub>FB</sub>	Error amplifier inverting input.		
6	7	COMP	Error amplifier output and compensation.		
7	8	RAMP	RAMP programmable with the external capacitor.		
8	9	IS+	Current sense amplifier non-inverting input.		
9	10	IS-	Current sense amplifier inverting input.		
10	11	IS COMP	Current sense amplifier compensation and output.		
11	12, 13	PGND	Power ground.		
12	14	V <sub>G</sub>	External power switch gate drive.		
13	15	V <sub>C</sub>	Output power stage supply voltage (8.0 V to 75 V).		
14	16	V <sub>D</sub>	External FET DRAIN voltage monitor.		
-	5	AGND	Analog ground.		
_	4	DGND	Digital ground.		

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
CS5101EN14	PDIP-14	
CS5101EN14G	PDIP-14 (Pb-Free)	25 Units / Rail
CS5101EDW16	SOIC-16WB	
CS5101EDW16G	SOIC-16WB (Pb-Free)	47 Units / Rail
CS5101EDWR16	SOIC-16WB	
CS5101EDWR16G	SOIC-16WB (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **CIRCUIT DESCRIPTION**

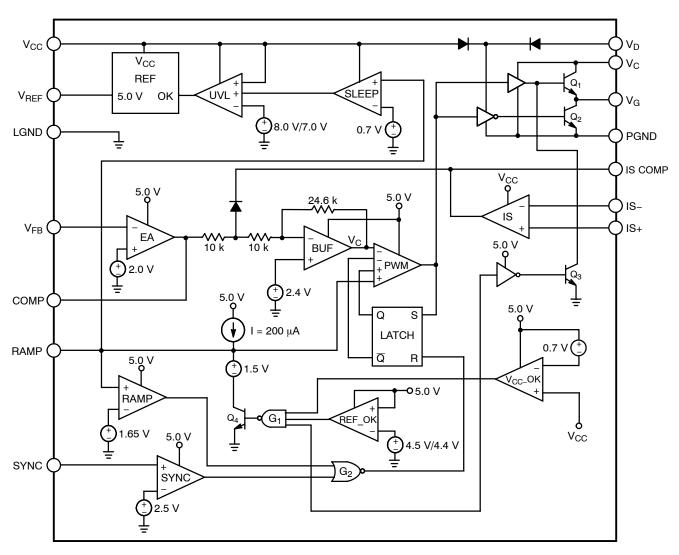


Figure 2. Block Diagram

#### **Theory of Operation**

The CS5101 is designed to regulate voltages in multiple output power supplies. Functionally, it is similar to a magnetic amplifier, operating as a switch with a delayed turn-on. It can be used with both single ended and dual ended topologies.

The  $V_{FB}$  voltage is monitored by the error amplifier EA. It is compared to an internal reference voltage and the amplified differential signal is fed through an inverting amplifier into the buffer, BUF. The buffered signal is compared at the PWM comparator with the ramp voltage generated by capacitor  $C_R$ . When the ramp voltage  $V_R$ , exceeds the control voltage  $V_C$ , the output of the PWM comparator goes high, latching its state through the LATCH, the output stage transistor  $Q_1$  turns on, and the external power switch, usually an N-FET, turns on.

#### **SYNC Function**

The SYNC circuit is activated at time  $t_1$  (Figure 3) when the voltage at the SYNC pin exceeds the threshold level (2.5V) of the SYNC comparator. The external ramp capacitor  $C_R$  is allowed to charge through the internal current source I (200  $\mu$ A). At time  $t_2$ , the ramp voltage intersects with the control voltage  $V_C$  and the output of the PWM comparator goes high, turning on the output stage and the external power switch. At the same time, the PWM comparator is latched by the RS latch, LATCH.

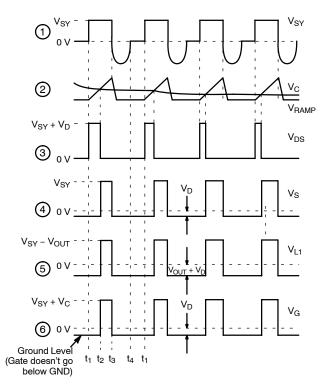


Figure 3. Waveforms for CS5101. The Number to the Left of Each Curve Refers to a Node On the Application Diagram on Page 2.

The logic state of the LATCH can be changed only when both the voltage level of the trailing edge of the power pulse at the SYNC pin is less than the threshold voltage of the SYNC comparator (2.5 V) and the RAMP voltage is less than the threshold voltage of the RAMP comparator (1.65 V). On the negative going transition of the secondary side pulse  $V_{SY}$ , gate  $G_2$  output goes high, resetting the latch at time  $t_3$ . Capacitor  $C_R$  is discharged through transistor  $Q_4$ .  $C_R$ 's output goes low disabling the output stage, and the external power switch (an N–FET) is turned off.

#### **RAMP Function**

The value of the ramp capacitor  $C_R$  is based on the switching frequency of the regulator and the maximum duty cycle of the secondary pulse  $V_{SY}$ .

If the RAMP pin is pulled externally to 0.3 V or below, the SSPR is disabled. Current drawn by the IC is reduced to less than  $100 \,\mu\text{A}$ , and the IC is in SLEEP mode.

#### **FAULT Function**

The voltage at the  $V_{CC}$  pin is monitored by the undervoltage lockout comparator with hysteresis. When  $V_{CC}$  falls below the UVL threshold, the 5.0 V reference and all the circuitry running off of it is disabled. Under this condition the supply current is reduced to less than 500  $\mu$ A.

The  $V_{CC}$  supply voltage is further monitored by the  $V_{CC}$ OK comparator. When  $V_{CC}$  is reduced below  $V_{REF}$  – 0.7 V, a fault signal is sent to gate  $G_1$ . This fault signal, which determines if  $V_{CC}$  is absent, works in conjunction with the ramp signal to disable the output, but only after the current cycle has finished and the RS latch is reset. Therefore this fault will not cause the output to turn off during the middle of an on pulse, but rather will utilize lossless turn–off. This feature protects the FET from overvoltage stress. This is accomplished through gate  $G_1$  by driving transistor  $O_4$  on.

An additional fault signal is derived from the REF\_OK comparator.  $V_{REF}$  is monitored so to disable the output through gate  $G_1$  when the  $V_{REF}$  voltage falls below the OK threshold. As in the  $V_{CC}$ \_OK fault, the REF\_OK fault disables the output after the current cycle has been completed. The fault logic will operate normally only when  $V_{REF}$  voltage is within the specification limits of REF\_OK.

### **DRAIN Function**

The drain pin,  $V_D$  monitors the voltage on the drain of the power switch and derives energy from it to keep the output stage in an off state when  $V_C$  or  $V_{CC}$  is below the minimum specified voltage.

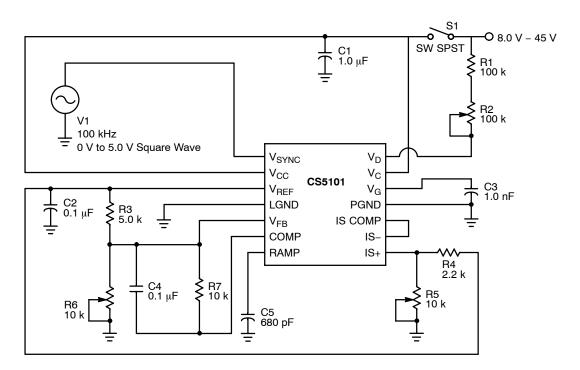
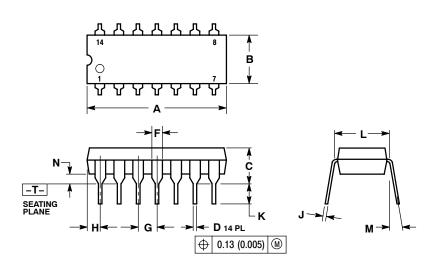


Figure 4. CS5101 Bench Test on DIP-14 Package

### **PACKAGE DIMENSIONS**

PDIP-14 CASE 646-06 ISSUE P

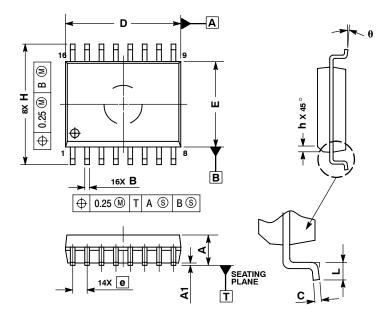


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	19.56
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
М		10 °		10 °
N	0.015	0.039	0.38	1.01

#### PACKAGE DIMENSIONS

SOIC-16WB CASE 751G-03 **ISSUE C** 



#### NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TO SERVICE AND TO S INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M. 1994.
- DIMENSIONS D AND E DO NOT INLCUDE
- MOLD PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  DIMENSION B DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	10.15	10.45		
Е	7.40	7.60		
е	1.27 BSC			
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
q	0 °	7 °		

#### **PACKAGE THERMAL DATA**

Parameter		PDIP-14	SOIC-16WB	Unit
$R_{ heta JC}$	Typical	23	48	°C/W
$R_{\theta JA}$	Typical	105	85	°C/W

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